To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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DATA SHEET

RENESAS

MOS INTEGRATED CIRCUIT

μPD3737

5150 PIXELS CCD LINEAR IMAGE SENSOR

DESCRIPTION

The μPD3737 is a 5150-pixel high sensitivity CCD (Charge Coupled Device) linear image sensor which changes optical images to electrical signal.

The μPD3737 has high speed CCD register, so it is suitable for high resolution scanners and facsimiles which scan high definition document at high speed.

FEATURES

- Valid photocell : 5150 pixels
- Photocell pitch : 7 μm
- High response sensitivity
- Peak response wavelength : 550 nm (green)
- Resolution : 16 dot/mm A3 (297 × 420 mm) size (shorter side)
  24 dot/mm A4 (210 × 297 mm) size (shorter side)
- High speed scan : 252 μs/line
- Drive clock level : CMOS output under +5 V operation
- Data rate : 20 MHz Max.
- Power supply : +12 V

ORDERING INFORMATION

Part Number	Package
μPD3737CY-A	CCD linear image sensor 32-pin plastic DIP (10.16 mm (400))

<R> **Remark** The μPD3737CY-A is a lead-free product.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

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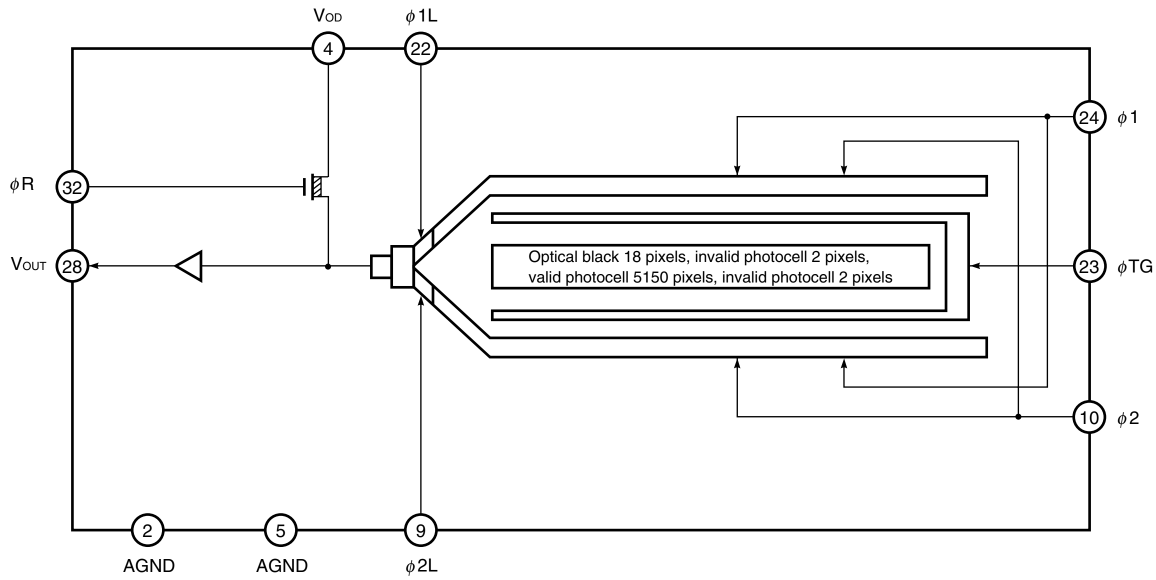
Date Published February 2006 NS CP (N)
Printed in Japan

The mark <R> shows major revised points.
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

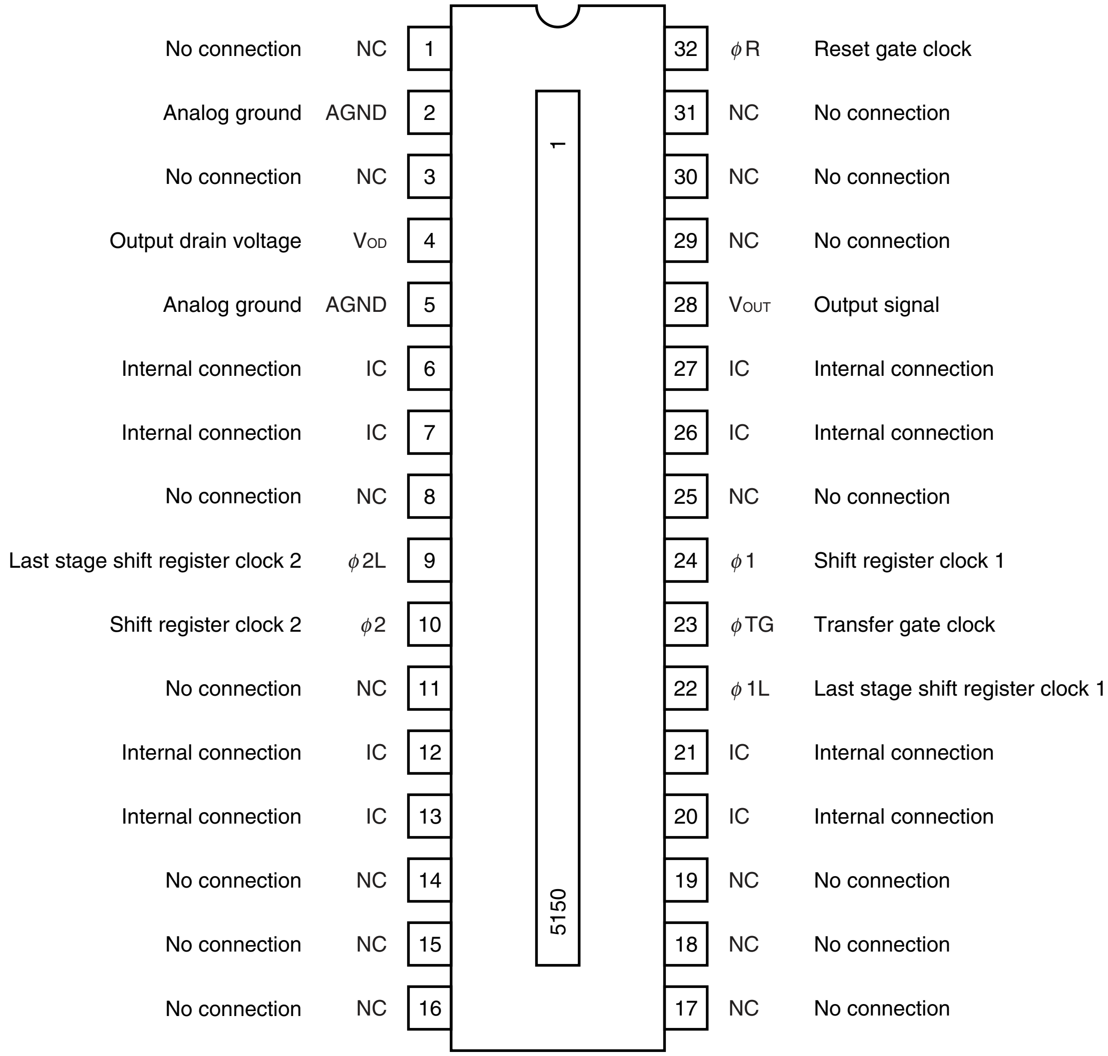
BLOCK DIAGRAM



PIN CONFIGURATION (Top View)

CCD linear image sensor 32-pin plastic DIP (10.16 mm (400))

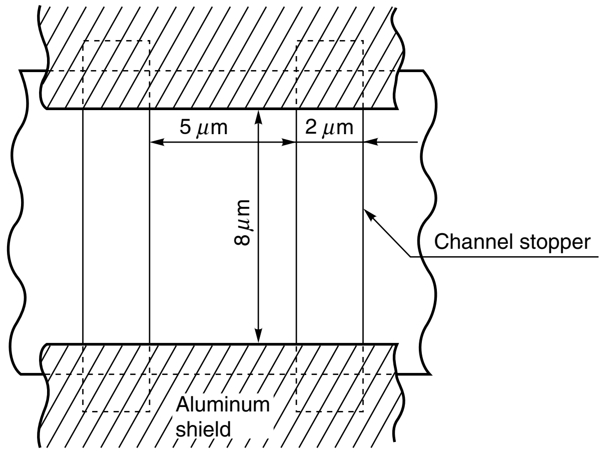
- μPD3737CY-A



Cautions 1. Leave pins 6, 7, 12, 13, 20, 21, 26, 27 (IC) unconnected.

2. Connect the No connection pins (NC) to GND.

PHOTOCELL STRUCTURE DIAGRAM



ABSOLUTE MAXIMUM RATINGS (T_A = +25°C)

Parameter	Symbol	Ratings	Unit
Output drain voltage	V_{OD}	–0.3 to +15	V
Shift register clock voltage	$V_{\phi 1}$, $V_{\phi 2}$	–0.3 to +8	V
Last stage shift register clock voltage	$V_{\phi 1L}$, $V_{\phi 2L}$	–0.3 to +8	V
Reset signal voltage	$V_{\phi R}$	–0.3 to +8	V
Transfer gate clock voltage	$V_{\phi TG}$	–0.3 to +8	V
Operating ambient temperature Note	T_A	0 to +60	°C
Storage temperature	T_{stg}	–40 to +70	°C

Note Use at the condition without dew condensation.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

RECOMMENDED OPERATING CONDITIONS (T_A = +25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Output drain voltage	V_{OD}	11.4	12.0	12.6	V
Shift register clock high level	$V_{\phi 1\_H}$, $V_{\phi 2\_H}$	4.5	5.0	5.5	V
Shift register clock low level	$V_{\phi 1\_L}$, $V_{\phi 2\_L}$	–0.3	0	+0.5	V
Last stage shift register clock high level	$V_{\phi 1LH}$, $V_{\phi 2LH}$	4.5	5.0	5.5	V
Last stage shift register clock low level	$V_{\phi 1LL}$, $V_{\phi 2LL}$	–0.3	0	+0.5	V
Reset signal φR high level	$V_{\phi RH}$	4.5	5.0	5.5	V
Reset signal φR low level	$V_{\phi RL}$	–0.3	0	+0.5	V
Transfer gate clock high level	$V_{\phi TGH}$	4.5	$V_{\phi 1\_H}$ Note	$V_{\phi 1\_H}$ Note	V
Transfer gate clock low level	$V_{\phi TGL}$	–0.3	0	+0.5	V
Shift register clock amplitude	$V_{\phi 1\_pp}$, $V_{\phi 2\_pp}$	4.5	5.0	5.8	V
Last stage shift register clock amplitude	$V_{\phi 1L\_pp}$, $V_{\phi 2L\_pp}$	4.5	5.0	5.8	V
Reset signal amplitude	$V_{\phi R\_pp}$	4.5	5.0	5.8	V
Transfer gate clock amplitude	$V_{\phi TG\_pp}$	4.5	5.0	5.8	V
Data rate	$f_{\phi R}$	0.5	1	20	MHz

Note When Transfer gate clock high level ($V_{\phi TGH}$) is higher than Shift register clock high level ($V_{\phi 1\_H}$), Image lag can increase.

Remarks 1. Input reset signal φR to pin 32 via capacitor (1000 pF ±20%, non polarity). Concerning the connection method refer to **APPLICATION CIRCUIT EXAMPLE**.

2. Operating conditions of reset signal φR is not the condition at device pins but the conditions of the signal which applied to capacitor.

ELECTRICAL CHARACTERISTICS

(T_A = +25°C, V_{OD} = 12 V, $f_{\phi 1}$ = 0.5 MHz, data rate = 1 MHz, storage time = 10 ms, input signal clock = 5 $V_{p\text{-}p}$, light source : 3200 K halogen lamp + C500 (infrared cut filter, t = 1 mm))

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Saturation voltage	V_{sat}		1.0	1.5	–	V
Saturation exposure	SE	Daylight color fluorescent lamp	–	0.2	–	lx•s
Photo response non-uniformity	PRNU	V_{OUT} = 500 mV	–	±5	±10	%
Average dark signal	ADS	Light shielding	–	2.0	6.0	mV
Dark signal non-uniformity	DSNU	Light shielding	–	6.0	12.0	mV
Power consumption	P_W		–	100	200	mW
Output impedance	Z_O		–	0.2	0.5	kΩ
Response	R_F	Daylight color fluorescent lamp	6.0	7.5	9.0	V/lx•s
Response peak			–	550	–	nm
Image lag	IL	V_{OUT} = 1.0 V	–	0.3	1.0	%
Offset level Note 1	V_{OS}		2.0	3.0	5.0	V
Output fall delay time Note 2	t_d	Time from 90% to 10% of ϕ2L fall is 5 ns	21	23	25	ns
Register imbalance	RI	V_{OUT} = 500 mV	–	0	4.0	%
Total transfer efficiency	TTE	V_{OUT} = 500 mV, data rate ($f_{\phi R1}$) = 20 MHz	92	98	–	%
Dynamic range	DR1	V_{sat}/DSNU	–	250	–	times
Reset feed-through noise Note 1	RFTN	Light shielding	–	250	500	mV

Notes 1. Refer to **TIMING CHART 2**.

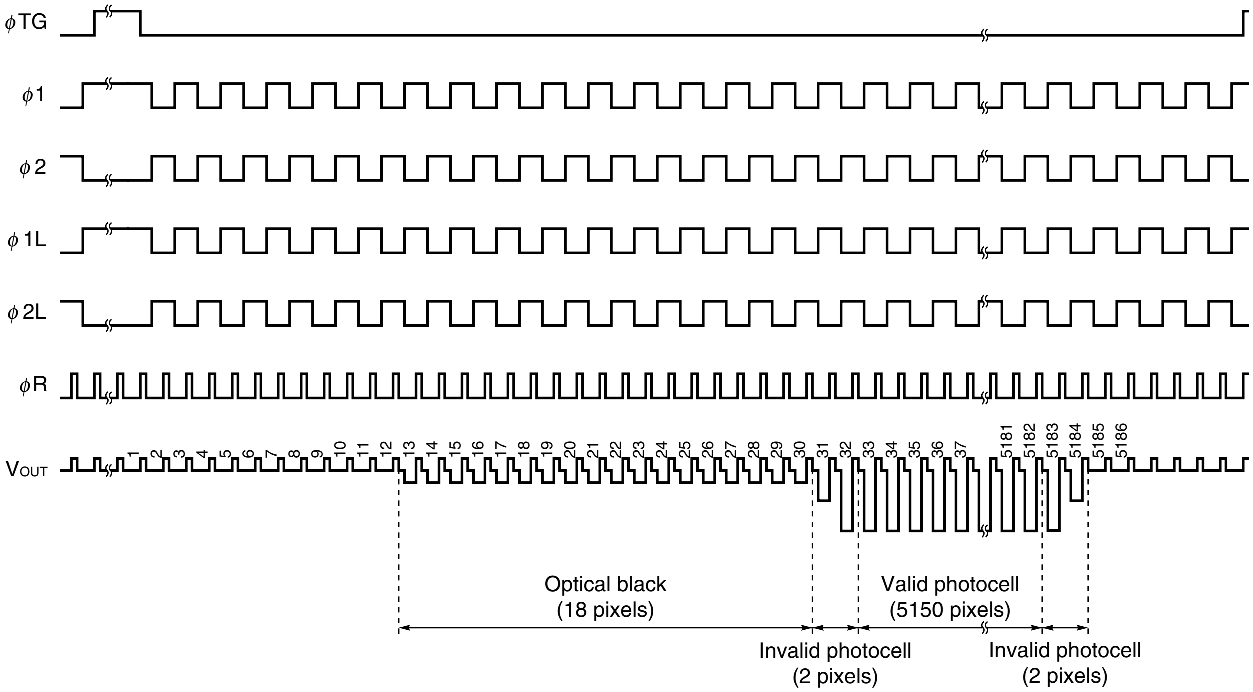
2. t_d is defined as a time from 10% of ϕ2L to 10% of V_{OUT}, output after passing through two steps of emitter follower in the **APPLICATION CIRCUIT EXAMPLE**.

INPUT PIN CAPACITANCE (T_A = +25°C, V_{OD} = 12 V)

Parameter	Symbol	Pin name	Pin No.	Min.	Typ.	Max.	Unit
Shift register clock pin capacitance 1	$C_{\phi 1}$	ϕ1	24	440	550	660	pF
Shift register clock pin capacitance 2	$C_{\phi 2}$	ϕ2	10	440	550	660	pF
Last stage shift register clock pin capacitance 1	$C_{\phi 1L}$	ϕ1L	22	40	50	60	pF
Last stage shift register clock pin capacitance 2	$C_{\phi 2L}$	ϕ2L	9	40	50	60	pF
Reset gate clock pin capacitance	$C_{\phi R}$	ϕR	32	8	10	12	pF
Transfer gate clock pin capacitance	$C_{\phi TG}$	ϕTG	23	120	150	180	pF

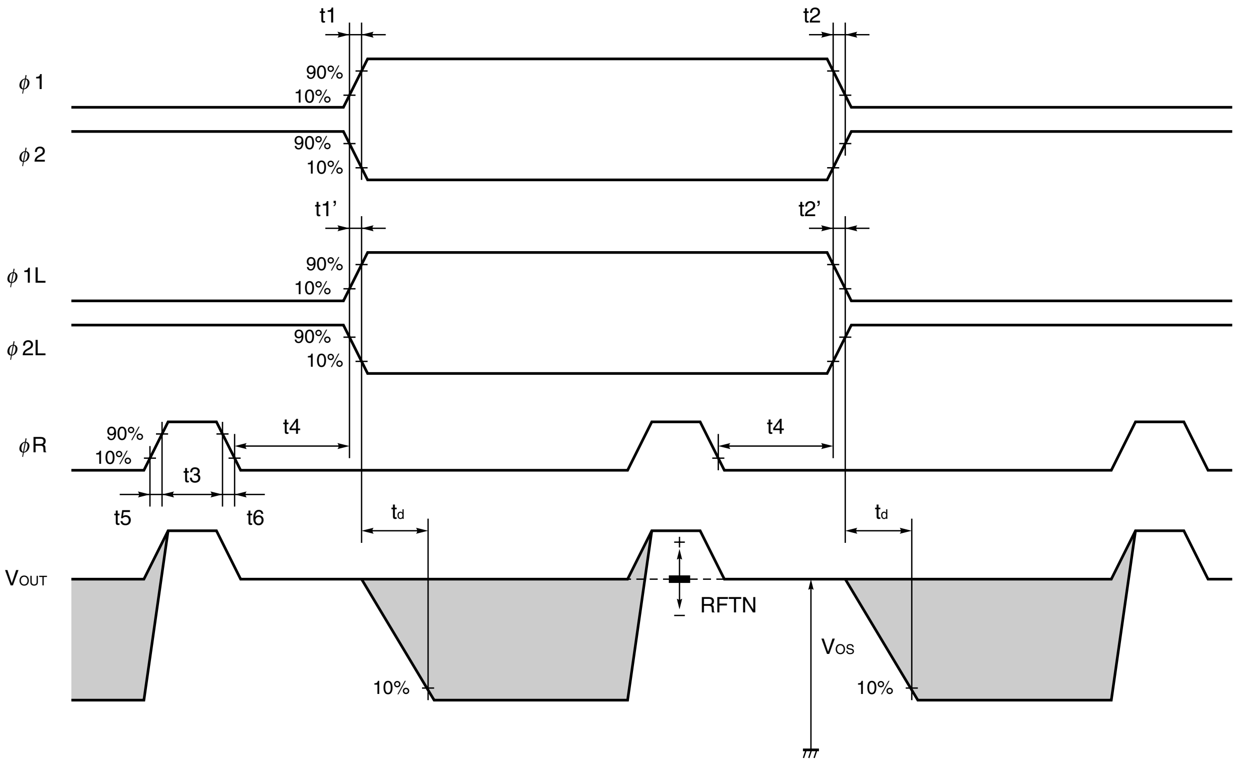
Remark $C_{\phi 1}$ and $C_{\phi 2}$ show the equivalent capacity of the real drive including the capacity of between ϕ1 and ϕ2.

TIMING CHART 1



Caution Input the φR pulse continuously during the high level period of φTG.

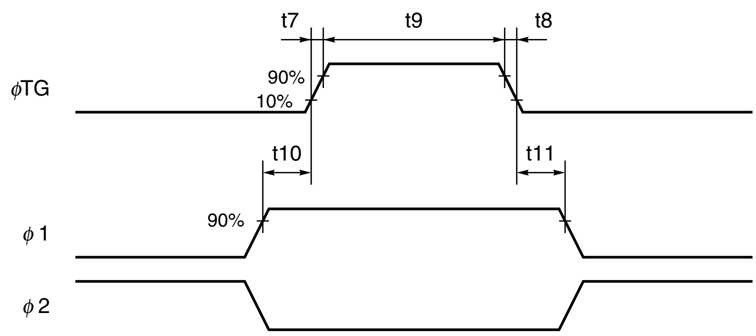
TIMING CHART 2



Symbol	Min.	Typ.	Max.	Unit
t1, t2	0	50	(150)	ns
t1', t2'	0	5	(25)	ns
t3	15	50	(500)	ns
t4	2	20	(500)	ns
t5, t6	0	20	(50)	ns

Remark The MAX. in the table above shows the operation range in which the output characteristics are kept almost enough for general purpose.

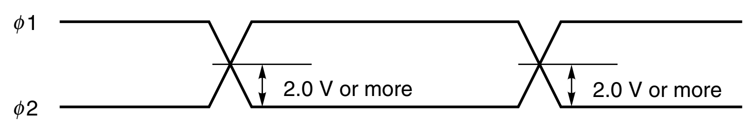
φTG, φ1, φ2 TIMING CHART



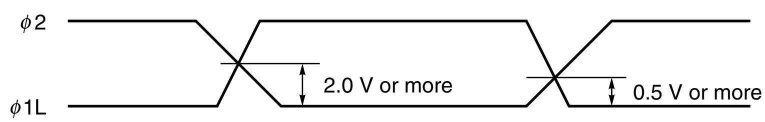
Symbol	Min.	Typ.	Max.	Unit
t7, t8	0	50	(100)	ns
t9	500	1000	10000	ns
t10, t11	0	100	10000	ns

Remark The MAX. in the table above shows the operation range in which the output characteristics are kept almost enough for general purpose.

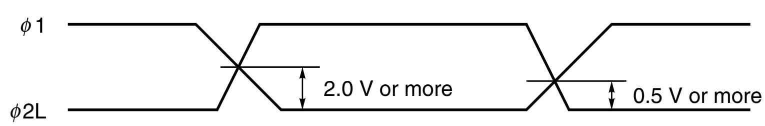
φ1, φ2 CROSS POINTS



φ1L, φ2 CROSS POINTS



φ1, φ2L CROSS POINTS



Remark Adjust cross points (φ1, φ2), (φ1L, φ2) and (φ1, φ2L) with input resistance of each pin.

DEFINITIONS OF CHARACTERISTIC ITEMS

1. Saturation voltage : **V_{sat}**
   Output signal voltage at which the response linearity is lost.

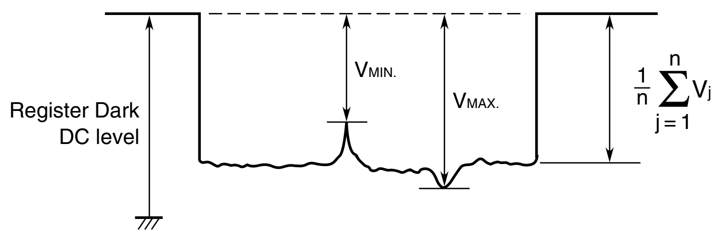
2. Saturation exposure : **SE**
   Product of intensity of illumination (lx) and storage time (s) when saturation of output voltage occurs.

3. Photo response non-uniformity : **PRNU**
   The peak/bottom ratio to the average output voltage of all the valid pixels calculated by the following formula.

$$\text{PRNU (\%)} = \left(\frac{V_{MAX.} \text{ or } V_{MIN.}}{\frac{1}{n}\sum_{j=1}^{n} V_j} - 1 \right) \times 100$$

n : Number of valid pixcels

V_j : Output voltage of each pixel

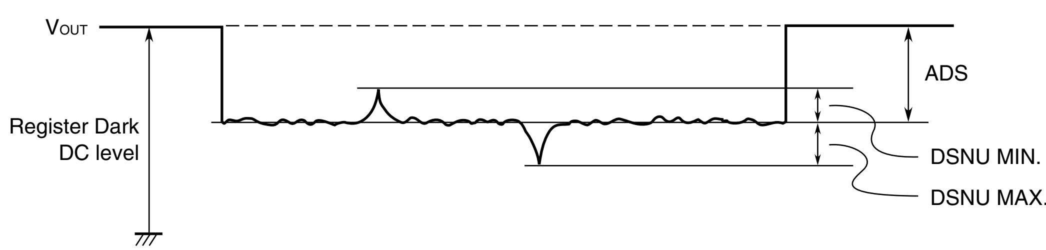


4. Average dark signal : **ADS**
   Average output signal voltage of all the valid pixels at light shielding. This is calculated by the following formula.

$$\text{ADS (mV)} = \frac{\sum_{j=1}^{5150} d_j}{5150}$$

d_j : Dark signal of valid pixel number j

5. Dark signal non-uniformity : **DSNU**
   The difference between ADS and voltage of the highest or lowest output pixel of all the valid pixels at light shielding.



6. Output impedance : **Zo**

   Impedance of the output pins viewed from outside.

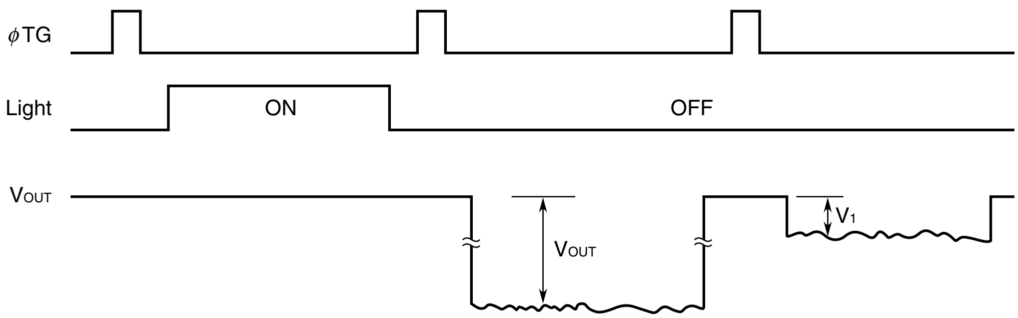
7. Response : **R**

   Output voltage divided by exposure (lx•s).

   Note that the response varies with a light source (spectral characteristic).

8. Image lag : **IL**

   The rate between the last output voltage and the next one after read out the data of a line.



$$IL\ (\%) = \frac{V_1}{V_{OUT}} \times 100$$

9. Register imbalance: **RI**

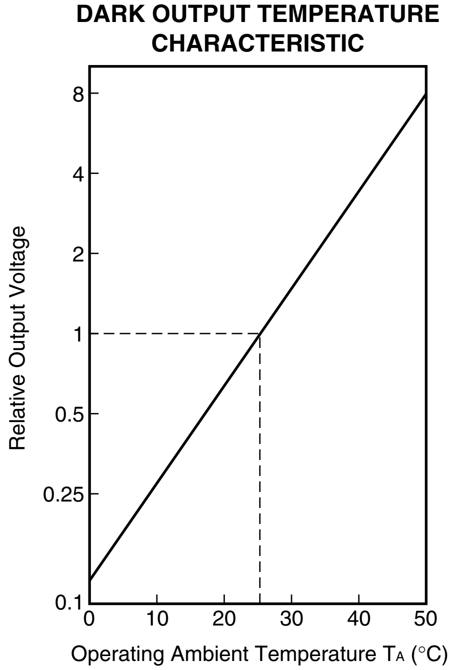
   The rate of the difference between the averages of the output voltage of Odd and Even pixels, against the average output voltage of all the valid pixels.

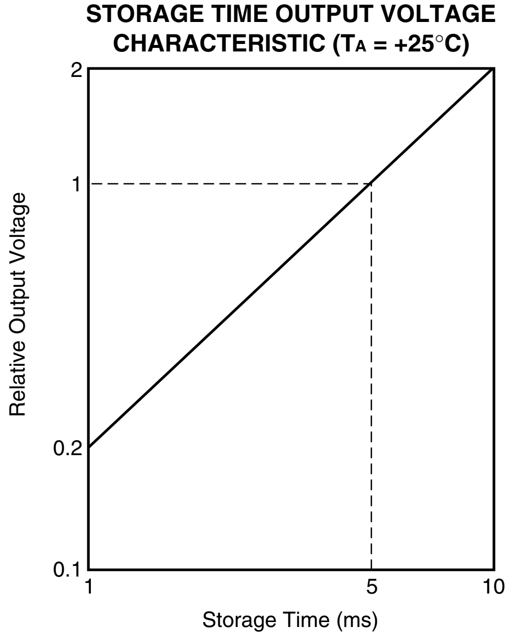
$$RI\ (\%) = \frac{\frac{2}{n}\left|\sum_{j=1}^{\frac{n}{2}} (V_{2j-1} - V_{2j})\right|}{\frac{1}{n}\sum_{j=1}^{n} V_j} \times 100$$

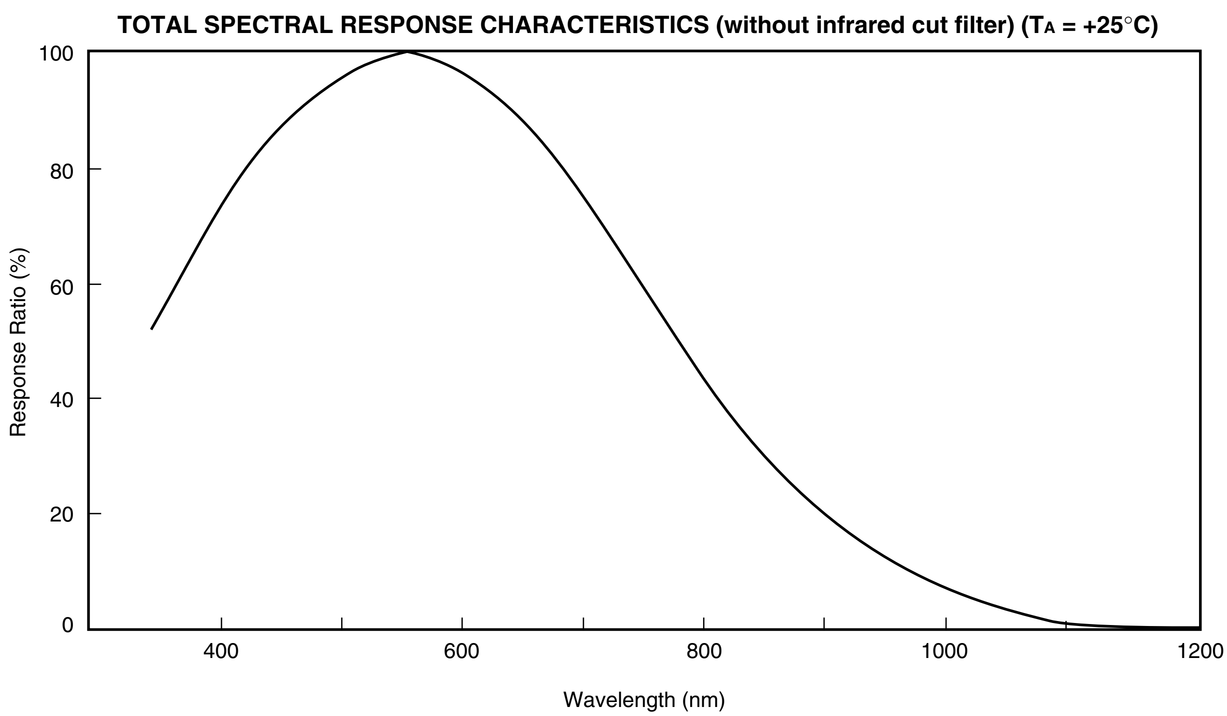
n : Number of valid pixels

V_j : Output voltage of each pixel

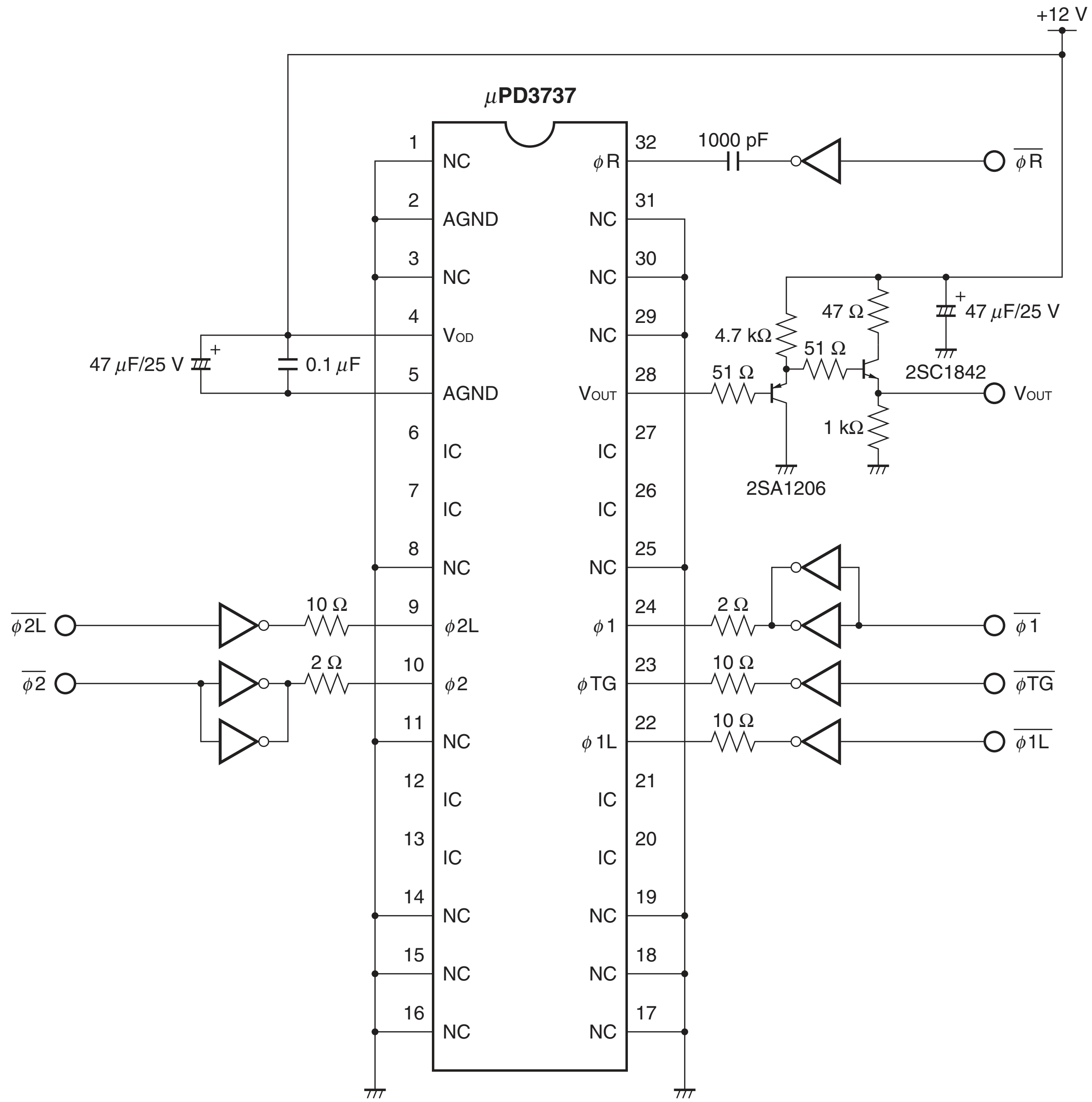
STANDARD CHARACTERISTIC CURVES (Reference Value)







APPLICATION CIRCUIT EXAMPLE



Cautions 1. Leave pins 6, 7, 12, 13, 20, 21, 26, 27 (IC) unconnected.

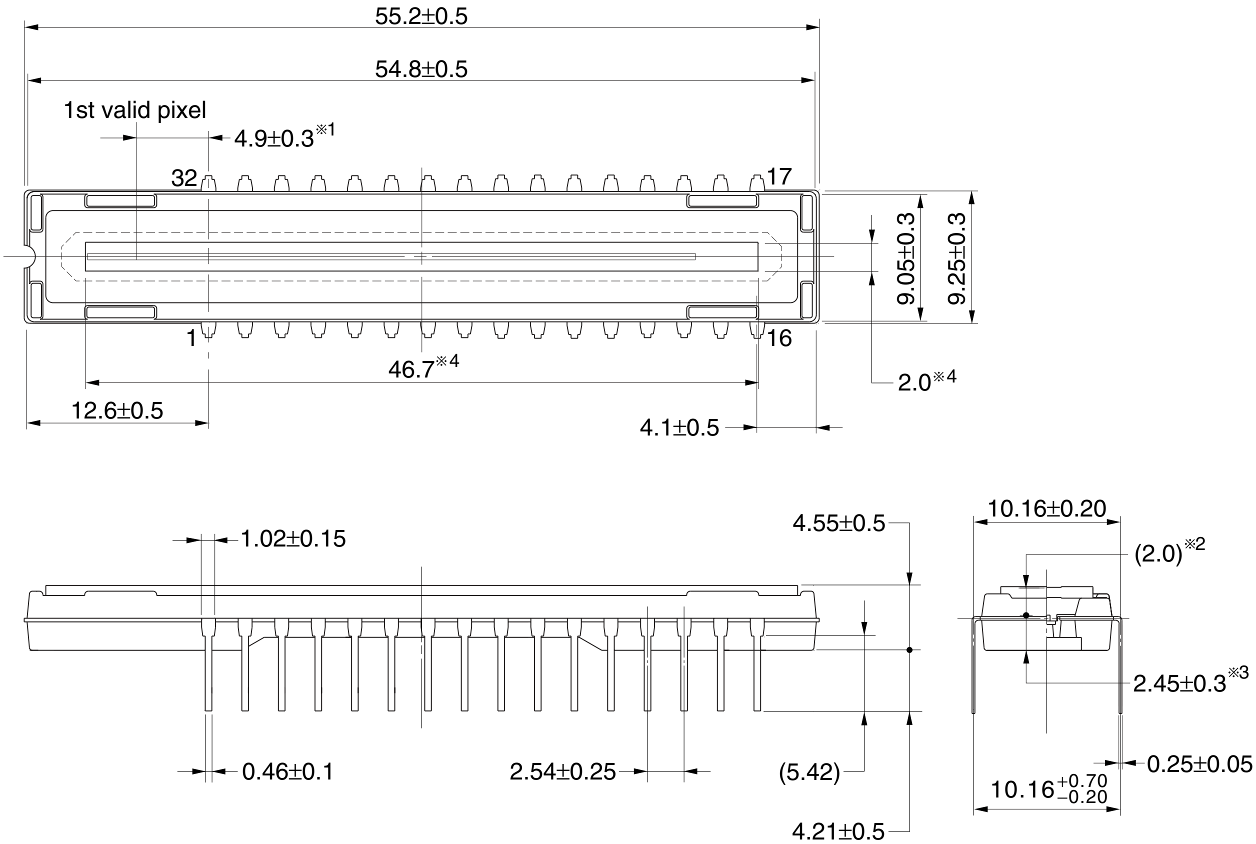
2. Connect the No connection pins (NC) to GND.

Remark The inverters shown in the above application circuit example are the 74AC04.

PACKAGE DRAWING

μPD3737CY
CCD LINEAR IMAGE SENSOR 32-PIN PLASTIC DIP (10.16 mm (400))

(Unit : mm)



Name	Dimensions	Refractive index
Plastic cap	52.2×6.4×0.8 (0.7※5)	1.5

※1 1st valid pixel ←→ The center of the pin1
※2 The surface of the CCD chip ←→ The top of the cap
※3 The bottom of the package ←→ The surface of the CCD chip
※4 Mirror finishied surface
※5 Thickness of mirror finished surface

32C-1CCD-PKG9-1

RECOMMENDED SOLDERING CONDITIONS

When soldering this product, it is highly recommended to observe the conditions as shown below.

If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

Type of Through-hole Device

μPD3737CY-A : CCD linear image sensor 32-pin plastic DIP (10.16 mm (400))

Process	Conditions
Partial heating method	Pin temperature : 350 °C or below, Heat time : 3 seconds or less (per pin)

Cautions 1. During assembly care should be taken to prevent solder or flux from contacting the glass cap. The optical characteristics could be degraded by such contact.

2. Soldering by the solder flow method may have deleterious effects on prevention of glass cap soiling and heat resistance. So the method cannot be guaranteed.

NOTES ON HANDLING THE PACKAGES

① DUST AND DIRT PROTECTING

The optical characteristics of the CCD will be degraded if the cap is scratched during cleaning. Don't either touch plastic cap surface by hand or have any object come in contact with plastic cap surface. Should dirt stick to a plastic cap surface, blow it off with an air blower. For dirt stuck through electricity ionized air is recommended. And if the plastic cap surface is grease stained, clean with our recommended solvents.

○ CLEANING THE PLASTIC CAP

Care should be taken when cleaning the surface to prevent scratches.

We recommend cleaning the cap with a soft cloth moistened with one of the recommended solvents below. Excessive pressure should not be applied to the cap during cleaning. If the cap requires multiple cleanings it is recommended that a clean surface or cloth be used.

○ RECOMMENDED SOLVENTS

The following are the recommended solvents for cleaning the CCD plastic cap.

Use of solvents other than these could result in optical or physical degradation in the plastic cap. Please consult your sales office when considering an alternative solvent.

Solvents	Symbol
Ethyl Alcohol	EtOH
Methyl Alcohol	MeOH
Isopropyl Alcohol	IPA
N-methyl Pyrrolidone	NMP

② MOUNTING OF THE PACKAGE

The application of an excessive load to the package may cause the package to warp or break, or cause chips to come off internally. Particular care should be taken when mounting the package on the circuit board. Don't have any object come in contact with plastic cap. You should not reform the lead frame. We recommended to use a IC-inserter when you assemble to PCB.

Also, be care that the any of the following can cause the package to crack or dust to be generated.

1. Applying heat to the external leads for an extended period of time with soldering iron.
2. Applying repetitive bending stress to the external leads.
3. Rapid cooling or heating

③ OPERATE AND STORAGE ENVIRONMENTS

Operate in clean environments. CCD image sensors are precise optical equipment that should not be subject to mechanical shocks. Exposure to high temperatures or humidity will affect the characteristics. So avoid storage or usage in such conditions.

Keep in a case to protect from dust and dirt. Dew condensation may occur on CCD image sensors when the devices are transported from a low-temperature environment to a high-temperature environment. Avoid such rapid temperature changes.

For more details, refer to our document "Review of Quality and Reliability Handbook" (C12769E)

④ ELECTROSTATIC BREAKDOWN

CCD image sensor is protected against static electricity, but destruction due to static electricity is sometimes detected. Before handling be sure to take the following protective measures.

1. Ground the tools such as soldering iron, radio cutting pliers of or pincer.
2. Install a conductive mat or on the floor or working table to prevent the generation of static electricity.
3. Either handle bare handed or use non-chargeable gloves, clothes or material.
4. Ionized air is recommended for discharge when handling CCD image sensor.
5. For the shipment of mounted substrates, use box treated for prevention of static charges.
6. Anyone who is handling CCD image sensors, mounting them on PCBs or testing or inspecting PCBs on which CCD image sensors have been mounted must wear anti-static bands such as wrist straps and ankle straps which are grounded via a series resistance connection of about 1 MΩ.

[MEMO]

[MEMO]

NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.

Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.